

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2004-307803

(43)Date of publication of application : 04.11.2004

(51)Int.Cl.

C08G 73/08

(21)Application number : 2003-325518

(71)Applicant : DAICEL CHEM IND LTD

(22)Date of filing : 18.09.2003

(72)Inventor : NAGANO SHINYA

HASHIMOTO HARUICHIRO

TSUTSUMI KIOHARU

FUNAKI KATSUNORI

(30)Priority

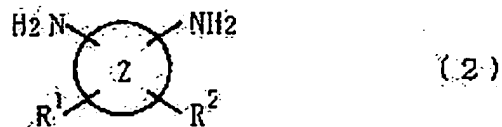
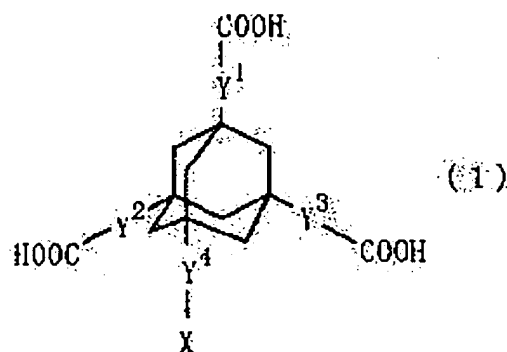
Priority number : 2003086164 Priority date : 26.03.2003 Priority country : JP

## (54) INSULATING FILM-FORMING MATERIAL AND INSULATING FILM

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a material forming a polybenzazole insulating film which has high heat resistance and a low dielectric constant and is useful for a semiconductor part and the like.

SOLUTION: The insulating film-forming material comprises a polymerizable composition obtained by dissolving an adamantane polycarboxylic acid represented by formula (1) (wherein X is a hydrogen atom, a carboxyl group or a hydrocarbon group; and Y1, Y2, Y3 and Y4 are the same or different and are each a single bond or a divalent aromatic cyclic group) and an aromatic polyamine represented by formula (2) (wherein the ring Z is a monocyclic or polycyclic aromatic ring; and R1 and R2 are each a substituent group bonded to the ring Z and are, same or different, an amino group, a mono-substituted amino group, a hydroxyl group or a mercapto group) in a solvent other than a ketone and an aldehyde.





---

**LEGAL STATUS**

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office



[First Hit](#)      [Previous Doc](#)      [Next Doc](#)      [Go to Doc#](#)

End of Result Set

☐ [Generate Collection](#) [Print](#)

L10: Entry 1 of 1

File: JPAB

Nov 4, 2004

PUB-NO: JP02004307803A

DOCUMENT-IDENTIFIER: JP 2004307803 A

TITLE: INSULATING FILM-FORMING MATERIAL AND INSULATING FILM

PUBN-DATE: November 4, 2004

## INVENTOR-INFORMATION:

NAME

COUNTRY

NAGANO, SHINYA

HASHIMOTO, HARUICHIRO

TSUTSUMI, KIYOHARU

FUNAKI, KATSUNORI

## ASSIGNEE-INFORMATION:

NAME

COUNTRY

DAICEL CHEM IND LTD

APPL-NO: JP2003325518

APPL-DATE: September 18, 2003

PRIORITY-DATA: 2003JP-086164 (March 26, 2003)

INT-CL (IPC): C08 G 73/08

## ABSTRACT:

PROBLEM TO BE SOLVED: To provide a material forming a polybenzazole insulating film which has high heat resistance and a low dielectric constant and is useful for a semiconductor part and the like.

SOLUTION: The insulating film-forming material comprises a polymerizable composition obtained by dissolving an adamantane polycarboxylic acid represented by formula (1) (wherein X is a hydrogen atom, a carboxyl group or a hydrocarbon group; and Y1, Y2, Y3 and Y4 are the same or different and are each a single bond or a divalent aromatic cyclic group) and an aromatic polyamine represented by formula (2) (wherein the ring Z is a monocyclic or polycyclic aromatic ring; and R1 and R2 are each a substituent group bonded to the ring Z and are, same or different, an amino group, a mono-substituted amino group, a hydroxyl group or a mercapto group) in a solvent other than a ketone and an aldehyde.

COPYRIGHT: (C) 2005, JPO&amp;NCIPI

[Previous Doc](#)      [Next Doc](#)      [Go to Doc#](#)